

**特征 Features**

- 反向漏电流低 Low reverse leakage
- 正向浪涌承受能力强 High forward surge capability
- 高信赖性 High reliability
- 高温焊接保证 High temperature soldering guaranteed:
260°C/10 秒
260°C/10seconds
- 引线和管体皆符合RoHS标准 Lead and body according with RoHS standard
- 型号后缀“-F”标记无卤素产品 Green compound with suffix "-F" on Marking

机械数据 Mechanical Data

- 封装外形:SMAF 塑封 Case:SMAF Molded plastic
- 环氧树脂 : UL易燃等级 : 94V-0
Epoxy: UL 94V-0 rate flame retardant
- 引脚 : 镀锡,无铅 Lead: Pure tin plated, lead free

最大值和特性 TA = 25°C 除非另有规定。

Maximum Ratings & Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

参数 Parameter	符号 Symbols	S2AF	S2BF	S2DF	S2GF	S2JF	S2KF	S2MF	单位 Unit
最大可重复峰值反向电压 Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
最大均方根电压 Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
最大直流阻断电压 Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
最大正向平均整流电流 Maximum average forward rectified current	I _{F(AV)}					2.0			A
正向不重复浪涌电流 8.3 ms单一正弦半波 Non-repetitive peak forward surge current 8.3 ms singlehalf sine-wave	I _{FSM}					50			A
最大正向电压 @IF=2.0A Maximum forward voltage	V _F					1.1			V
最大反向电流 @V _{DC} TA= 25°C Maximum reverse current TA= 125°C	I _R				5				μA
					100				
典型热阻 Typical thermal resistance (Note 1)	R _{θJA}				85				°C/W
典型结电容 VR=4.0V,f=1MHz Type junction capacitance	C _J				20				pF
工作结温和存储温度 Operating junction and storage temperature rang	T _J , T _{STG}				-55 --- +150				°C

备注 Note:

1) 安装在PCB板上，从PN结到周围环境的热阻。

1) Thermal resistance from junction to ambient, PCB mounted.

特性曲线 Characteristic Curves
